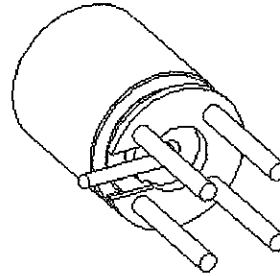
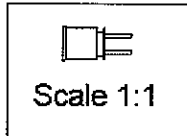
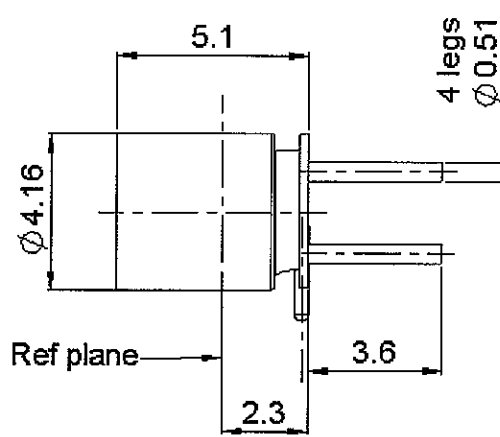
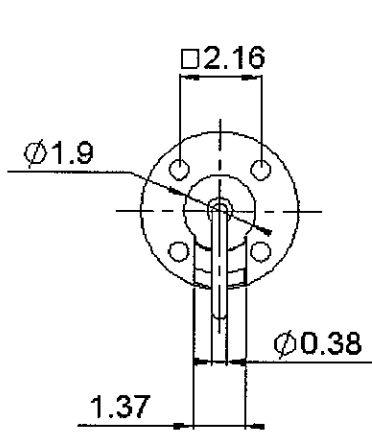


**STRAIGHT MALE RECEPTACLE FOR PCB**

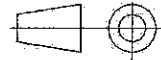
**R222.428.000**

**PIN IN PASTE - FULL DETENT**

Series : SMP



All dimensions are in mm.



| COMPONENTS     | MATERIALS               | PLATINGS (µm)                       |
|----------------|-------------------------|-------------------------------------|
| BODY           | STAINLESS STEEL + BRASS | PASSIVATED + GOLD 0.5 OVER NICKEL 2 |
| CENTER CONTACT | BERYLLIUM COPPER        | GOLD 1.27 OVER NICKEL 1.27          |
| OUTER CONTACT  |                         |                                     |
| INSULATOR      | PTFE                    |                                     |
| GASKET         |                         |                                     |
| OTHERS PARTS   | -                       | -                                   |
| -              | -                       | -                                   |
| -              | -                       | -                                   |

Issue : 0529 B

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



**STRAIGHT MALE RECEPTACLE FOR PCB**

**R222.428.000**

**PIN IN PASTE - FULL DETENT**

Series : SMP

**PACKAGING**

| Standard | Unit       | Other      |
|----------|------------|------------|
| 100      | 'W' option | Contact us |

**SPECIFICATION**

**ELECTRICAL CHARACTERISTICS**

**ENVIRONMENTAL**

|                                 |        |                      |
|---------------------------------|--------|----------------------|
| Impedance                       |        | 50 Ω                 |
| Frequency                       |        | 0-12 GHz             |
| VSWR                            | 1.15 + | 0.000 x F(GHz) Maxi  |
| Insertion loss                  |        | 0.12 √F(GHz) dB Maxi |
| RF leakage                      | - (    | NA - F(GHz)) dB Maxi |
| Voltage rating                  |        | 335 Veff Maxi        |
| Dielectric withstanding voltage |        | 500 Veff mini        |
| Insulation resistance           |        | 5000 MΩ mini         |

|                       |              |
|-----------------------|--------------|
| Operating temperature | -65/+165 °C  |
| Hermetic seal         | NA Atm.cm3/s |
| Panel leakage         | NA           |

**OTHERS CHARACTERISTICS**

Assembly instruction

Others :  
Compliant with MIL-STD-348

**MECHANICAL CHARACTERISTICS**

|                            |       |             |
|----------------------------|-------|-------------|
| Center contact retention   |       |             |
| Axial force – Mating end   | 6.8   | N mini      |
| Axial force – Opposite end | 6.8   | N mini      |
| Torque                     |       | N.cm mini   |
| Recommended torque         |       |             |
| Mating                     | NA    | N.cm        |
| Panel nut                  | NA    | N.cm        |
| Mating life                | 100   | Cycles mini |
| Weight                     | 0.320 | g           |

Issue : 0529 B

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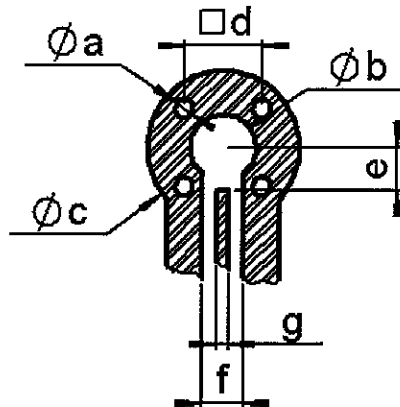
**STRAIGHT MALE RECEPTACLE FOR PCB**

**PIN IN PASTE - FULL DETENT**

**R222.428.000**

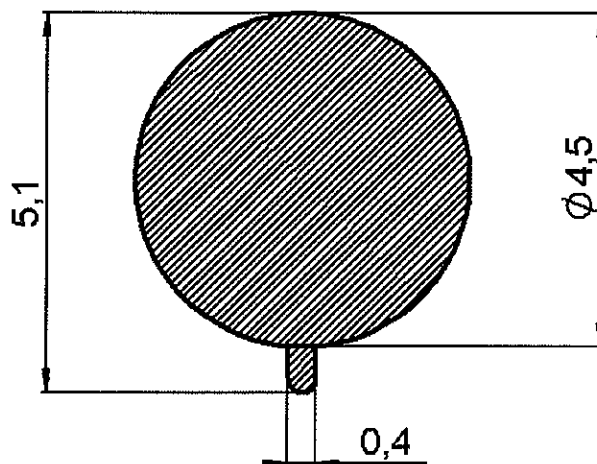
Series : SMP

**PCB mounting hole pattern**



|   |           |
|---|-----------|
| a | 0,63      |
| b | 1,9       |
| c | 4,45 min. |
| d | 2,16      |
| e | 2,29 max. |
| f | 1,52 max. |
| g | ,45 min.  |

**SHADOW FOR VIDEO CAMERA**



Issue : 0529 B

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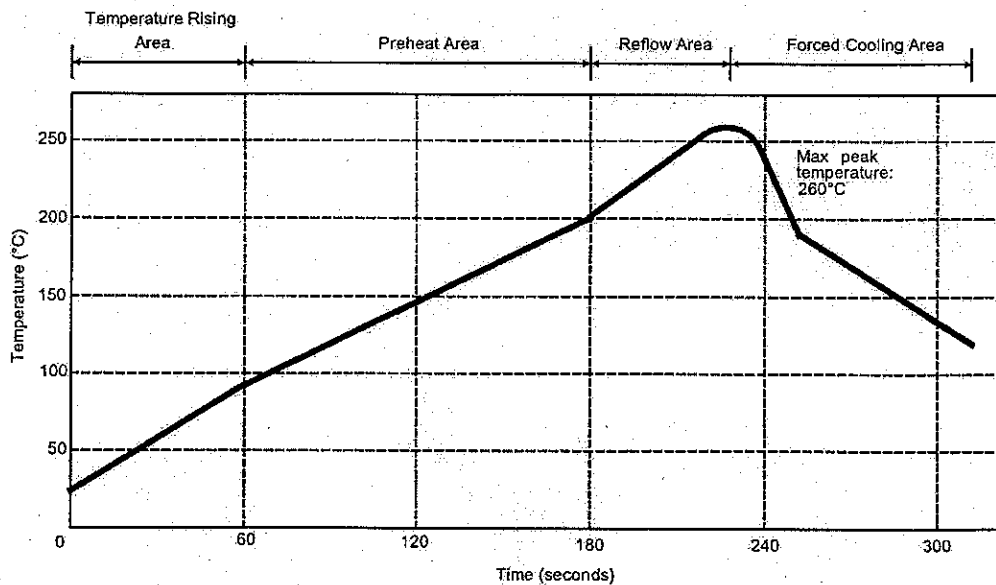
**PIN IN PASTE - FULL DETENT**

Series : SMP

**SOLDER PROCEDURE**

1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.  
We advise a thickness of 150 microns ( 5.85 microinch ). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.  
Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.
3. Soldering by infra-red reflow.  
Below, please find the typical profile to use.
4. Cleaning of printed circuit boards.
5. Checking of solder joints and position of the component by visual inspection.

**TEMPERATURE PROFILE**



| Parameter                        | Value    | Unit   |
|----------------------------------|----------|--------|
| Temperature rising Area          | 1 - 4    | °C/sec |
| Max Peak Temperature             | 260      | °C     |
| Max dwell time @260°C            | 10       | sec    |
| Min dwell time @235°C            | 20       | sec    |
| Max dwell time @235°C            | 60       | sec    |
| Temperature drop in cooling Area | -1 to -4 | °C/sec |
| Max dwell time above 100°C       | 420      | sec    |

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